

DATA SHEET

MODULETEK –XFP-10GB-BIDI-T1330/R1270-20KM-C10

10 Gigabit XFP Tx1330nm/Rx1270nm Bi-directional Transceiver

XFP-10GB-BIDI-T1330/R1270-20KM-C10 Overview

ModuleTek's XFP-10GB-BIDI-T1330/R1270-20KM-C10 10Gb/s XFP optical transceivers are designed for the IEEE 802.3ae 10GBASE-LR, 10GBASE-LW and 10GFC 1200-SM-LL-L interconnects. The XFP-10GB-BIDI-T1330/R1270-20KM-C10 are compliant with the XFP Multi-Source Agreement (MSA) Specification. The digital diagnostics functions are available via the 2-wire serial interface, as specified in the XFP MSA.

Product Features

- Supports from 9.95 Gb/s to 11.3 Gb/s bit rates.
- Compliant with IEEE 802.3ae, 10GBASE–LR/LW, 10GFC application.
- Compliant with XFP MSA.
- 30 pin XFP compatible connector.
- Standard bail mechanism for consistent installation and removal
- Built–in digital diagnostic functions.
- Hot Pluggable XFP footprint.
- 1330nm DFB laser transmitter and 1270 PIN Receiver
- Simplex LC connector
- Up to 20km on SMF
- RoHS Compliant
- Operating temperature range: 0°C to 70°C

Applications

- 10GBASE–LR 10G Ethernet
- 10GBASE–LW 10G Ethernet
- 1200–SM–LL–L 10G Fiber Channel

Ordering Information

Part Number	Description	Color on Clasp
XFP-10GB-BIDI-T1330/R1270-20KM-C10	10 Gigabit XFP BIDI, Tx1330nm/Rx1270nm, LC Connectors 20km on SMF, with DOM function.	blue
For More Information: ModuleTek Limited Web: www.moduletek.com Email: sales@moduletek.com		

Absolute Maximum Ratings

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Storage Ambient Temperature	T _S	-40		85	°C	
Supply Voltage 3.3V	V _{CC3}	-0.5		4	V	

General Specifications

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Data Rate	DR	9.95		11.3	Gb/s	1
Bit Error Rate	BER			10^{-12}		
Total Power Consumption	P			3.5	W	
Supply Voltage-3.3V	V _{CC3}	3.14		3.46	V	2
Supply Current-V _{CC3} supply	I _{CC3}			750	mA	
Case Operating Temperature	T _C	0		70	°C	

Notes:

- 10GBASEZ-LR/LW 1200-SM-LL-L
- Operating Environment

Link Distances

Parameter	Fiber Type	Distance Range (km)
9.95 – 11.3 Gb/s	9/125um SMF	20

Optical - Characteristics - Transmitter

$V_{CC3}=3.14V$ to $3.46V$, $T_C=0^{\circ}C$ to $70^{\circ}C$

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Optical Center Wavelength	λ_C	1320	1330	1340	nm	
Output Optical Power	P_{TX}	-8.2		0.5	dBm	1
Extinction Ratio	ER	3.5			dB	
Side Mode Suppression Ratio	SMSR	30			dB	
Relative Intensity Noise	RIN			-130	dB/Hz	
Transmitter Dispersion Penalty	TDP			3.2	dB	
Launch Power of OFF Transmitter	P_{OUT_OFF}			-30	dBm	1
Transmitter Jitter	According to IEEE 802.3ae requirement					

Notes:

1. Average

Optical - Characteristics - Receiver

$V_{CC3}=3.14V$ to $3.46V$, $T_C=0^{\circ}C$ to $70^{\circ}C$

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Center Wavelength Range	λ_C	1260	1270	1280	nm	
Optical Input Power	P_{RX}	-14.4		0.5	dBm	
Receiver Sensitivity in (OMA)@10.3Gb/s	R_{X_SEN1}			-12.6	dBm	1
Stressed Receiver Sensitivity in OMA @10.3Gb/s	R_{X_SEN2}			-10.3	dBm	2
Receiver Reflectance	TR_{RX}			-12	dB	
LOS Assert	LOS_A	-32			dBm	
LOS De-Assert	LOS_D			-18	dBm	
LOS Hysteresis	LOS_H	0.5			dB	

Notes:

1. Measured with worst ER: $BER < 10^{-12}$; $2^{31}-1$ PRBS
2. IEEE 802.3ae

Electrical - Characteristics - Transmitter

$V_{CC3}=3.14V$ to $3.46V$, $T_C=0^{\circ}C$ to $70^{\circ}C$

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Input differential impedance	R_{IN}		100		Ω	1
Differential data input swing	V_{IN_PP}	120		820	mV	
Transmit Disable Voltage	V_D	2		V_{CC}	V	2
Transmit Enable Voltage	V_{EN}	GND		$GND+0.8$	V	
Transmit Disable Assert Time				10	us	

Notes:

1. After internal AC coupling
2. Or open circuit

Electrical - Characteristics - Receiver

$V_{CC3}=3.14V$ to $3.46V$, $T_C=0^{\circ}C$ to $70^{\circ}C$

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Differential data output swing	V_{OUT_PP}	340	650	850	mV	
Data output rise time (20%-80%)	T_R			38	ps	1
Data output fall time(20%-80%)	T_F			38	ps	1
LOS Fault	V_{LOS_A}	$V_{CC}-0.5$		V_{CC_HOST}	V	
LOS Normal	V_{LOS_D}	GND		$GND+0.5$	V	

Notes:

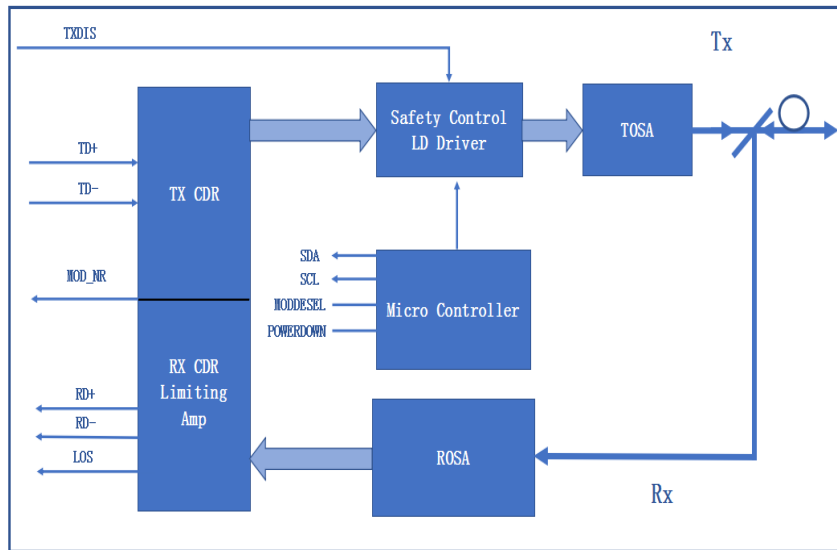
- 1.20%-80%

Digital Diagnostic Functions

ModuleTek's XFP-10GB-BIDI-T1330/R1270-20KM-C10 incorporates a XFP compliant 2-wire management interface which is used for serial ID, digital diagnostics, and certain control functions. It is modeled on the SFF-8472 Rev 9.3 specification modified to accommodate a single 2-wire interface address. In addition to the basic I2C read/write functionality the modules support packet error checking that, when enabled, allows the host system to confirm the validity of any read data. Details of the protocol and interface are explicitly described in the MSA. And the digital diagnostic functions via a 2-wire serial interface can provide real-time access to following operating parameters:

- a. Transceiver Temperature
- b. Laser Bias Current
- c. Transmitted Optical Power
- d. Received Optical Power
- e. Transceiver Supply Voltage

Block-Diagram-of-Transceiver



Transmitter Section

The DFB driver accepts differential input data and provide bias and modulation currents for driving a laser. An automatic power-control (APC) feedback loop is incorporated to maintain a constant average optical power. DFB laser in an eye safe optical subassembly (OSA) mates to the fiber cable.

TX_DISABLE

TX_DIS is a input pin. When TX_DIS is asserted High, the XFP module transmitter output must be turned off.

Receiver Section

The Receiver utilizes a PIN detector integrated with a trans-impedance preamplifier in an OSA. The OSA is connected to a limiting Amplifier which providing post-amplification quantization, and optical signal detection. The limiting amplifier is AC coupled to the Trans-impedance amplifier, with internal 100ohm differential termination. RX CDR is used to overcomes host board degradations by reshaping, regenerating, and attenuating jitter.

Receive (RX_LOS)

The RX_LOS of an output pin, when LOS is high, it indicates insufficient optical power for reliable signal reception.

MODNR:

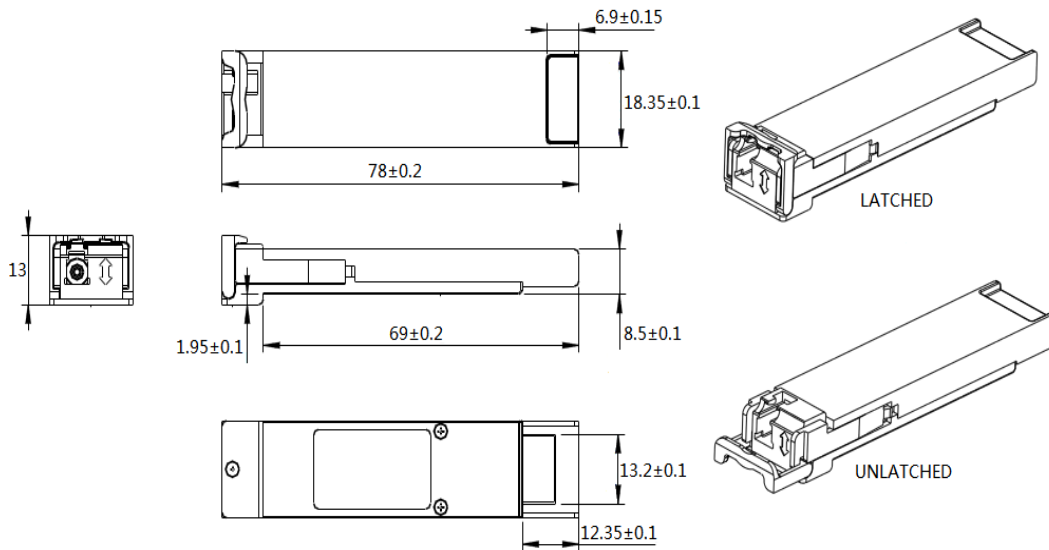
The MODNR is an output pin that when High, indicates that the module has detected a condition that renders transmitter and or receiver data invalid, shall consist of logical OR of the following signals:

- f. Transmit Signal Conditioner Loss of Lock
- g. Transmitter Laser Fault
- h. Receiver Signal Conditioner Loss of Lock

Controller Section

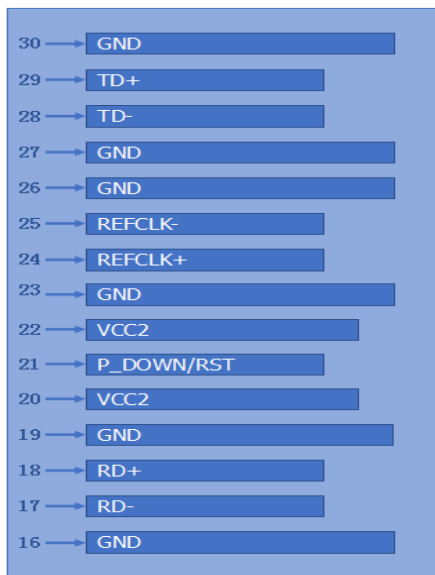
The micro controller unit initializes the control register of laser driver, limiting amplifier and CDR. And monitors the running information from the laser driver, limiting amplifier and CDR. Then report these information to the customer.

Dimensions

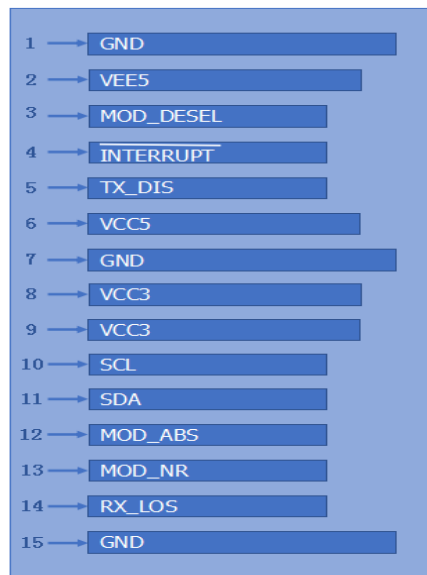


ALL DIMENSIONS ARE ± 0.2 mm UNLESS OTHERWISE SPECIFIED
UNIT: mm

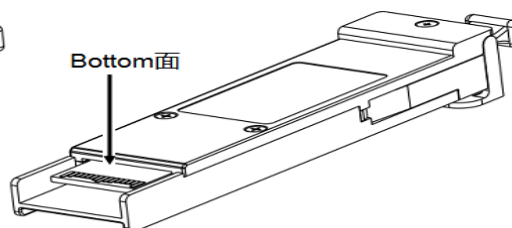
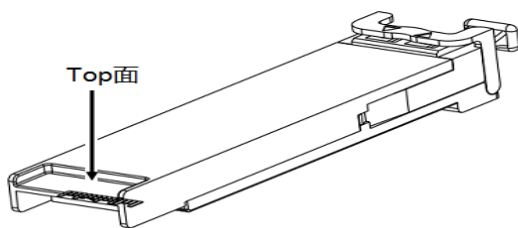
Electrical Pad Layout



Top of Board



Bottom of Board



Pin Assignment – Pin1 to Pin30

PIN #	Symbol	Logic	Description	Remarks
1	GND		Module Ground	1
2	VEE5		Optional –5.2 Power Supply (Not required)	
3	Mod–Desel	LVTTTL–I	Module De-select, when held low allows the module to respond to 2-wire serial interface commands	
4	Interrupt	LVTTTL–O	Indicates presence of an important condition which can be read over the serial 2-wire interface	2
5	TX_DIS	LVTTTL-I	Transmitter Disable, Transmitter laser source turned off	
6	VCC5		+5V Power Supply	
7	GND		Module Ground	3
8	VCC3		+3.3V Power Supply	
9	VCC3		+3.3V Power Supply	
10	SCL	LVTTTL-I	Serial 2-wire interface clock	4
11	SDA	LVTTTL-I/O	Serial 2-wire interface data line	4
12	Mod_ABS	LVTTTL-O	Module Absent; Indicates module is not present. Grounded in the module	4
13	Mod_NR	LVTTTL-O	Module Not Ready; Indicates module operating fault	4
14	RX_LOS	LVTTTL-O	Receiver Loss of Signal indicator	4
15	GND		Module Ground	3
16	GND		Module Ground	3
17	RD-	CML-O	Receiver inverted data output	
18	RD+	CML-O	Receiver non-inverted data output	
19	GND		Module Ground	3
20	VCC2		+1.8V Power Supply	
21	P_Down/RST	LVTTTL-I	Power Down; When high, places the module in the low power stand-by mode and on the falling edge of P_Down initiates a module rest	
			Reset; The falling edge initiates a complete reset of the module including the 2-wire serial interface, equivalent to a power cycle	
22	VCC2		+1.8V Power Supply	
23	GND		Module Ground	3
24	RefCLK+	PECL-I	Reference Clock non-inverted input, AC coupled on the host board	

25	RefCLK-	PECL-I	Reference Clock inverted input, AC coupled on the host board	
26	GND		Module Ground	3
27	GND		Module Ground	3
28	TD-	CML-I	Transmitter inverted data input	
29	TD+	CML-I	Transmitter non-inverted data input	
30	GND		Module Ground	3

Notes:

1. Module ground pins (GND) are isolated from the module case and chassis ground within the module
2. Open collector, should be pulled up with 4.7kΩ-10kΩ on host board to a voltage between 3.15V and 3.6V
3. Same as Pin # 1
4. Same as Pin # 4

References

1. 10 Gigabit Small Form Factor Pluggable Module(XFP)Multi-Source Agreement(MSA), Rev4.5 – August 2005.